

WHAT IS CLAIMED IS:

1. A method of manufacturing an electronic part in which that side of an insulating member sandwiched between conductor film and a lower conductor layer
5 which is adjacent to said conductor film, a conductor portion connected from said lower conductor layer is exposed, comprising
forming an opening portion having said lower conductor layer as a bottom in the formed area of
10 said conductor portion from said conductor film side,
growing metal plating layer from the bottom of said opening portion with said lower conductor layer as an electrode,
growing metal plating layer on the upper
15 surfaces of said conductor film and said conductor portion with said conductor film and said conductor portion as electrodes after said metal plating layer has reached said conductor film to thereby form said conductor portion in said opening portion, and
20 forming a thickness enough to form an upper conductor layer.

2. A method of manufacturing an electronic part in which on the upper surface of an insulating member
25 covering a lower conductor layer, a conductor portion connected from said lower conductor layer is exposed, comprising

forming conductor film on the upper surface of
said insulating member and protective film formed on
a part of said insulating member in a thickness
direction, and thereafter forming an opening portion
5 having said lower conductor layer as a bottom in said
protective film and said conductor film in the formed
area of said conductor portion,

growing metal plating layer from the bottom of
said opening portion with said lower conductor layer
10 as an electrode, and

growing metal plating layer on the upper
surfaces of said conductor film and said conductor
portion with said exposed conductor film and said
conductor portion on which protective film is not
15 formed as electrodes, to thereby form a thickness
enough to form an upper conductor layer after said
metal plating layer has reached said conductor film
to thereby form said conductor portion in said
opening portion.

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3. A method according to Claim 1 or 2, wherein
said exposed conductor film providing said electrode
is set outside a product area.

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4. A method according to Claim 1 or 2, wherein
said insulating member and said conductor film are
made integral with each other in advance.

5. An electronic part having structure in which
an upper conductor layer is formed on the upper
surface of an insulating member covering a lower
5 conductor layer, and

said lower conductor layer and said upper
conductor layer are connected together by a conductor
portion extending through said insulating member,
wherein said conductor portion forming the connection
10 between said lower conductor layer and said upper
conductor layer, and an upper predetermined thickness
in said upper conductor layer are formed by only the
precipitation of a metal by electroplating.